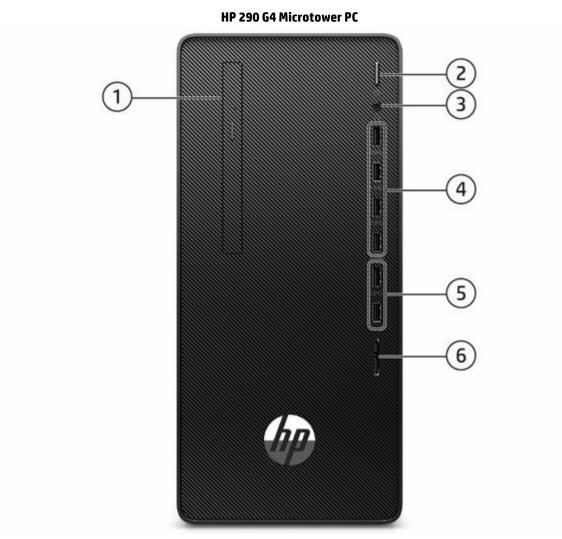
Overview

QuickSpecs



Front

- 1. Slim-height Bay supporting an optical disk drive (Optional)
- 2. Power Button
- 3. Combo jack, Headphone/ Microphone
- 4. (4) SuperSpeed USB 5Gbps port²
- 5. (2) SuperSpeed USB 10Gbps port²
- 6. SD Card Reader (Optional)

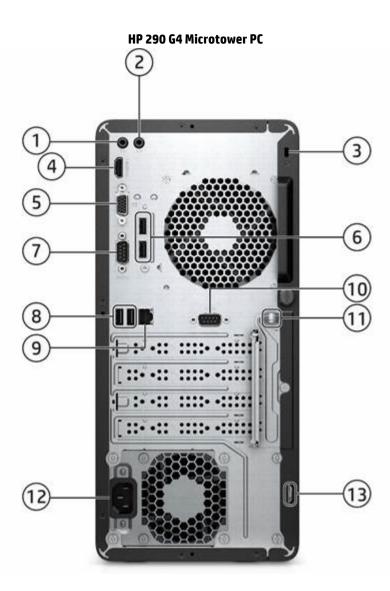
Not Shown

- Slots (1) PCI Express x16
 - (1) PCI Express x1
 - (1) PCI¹
 - (1) M.2 for WLAN
 - (1) M.2 2242/2280 storage
- Bays (1) 3.5" or 2.5" internal HDD bay
 - (1) 3.5" or 2.5" internal HDD bay (share bay with caddy)
 - (1) 9.5mm internal optical drive bay

1. Available on select skus only.

2. SuperSpeed USB 10Gbps = USB 3.2 Gen2. SuperSpeed USB 5Gbps = USB 3.2 Gen1

Overview



Back

- 1. Audio Line out
- 2. Audio Line in
- 3. Standard lock slot
- 4. HDMI Port¹
- 5. VGA Port¹
- 6. Connector (2) USB 2.0 port (Optional)³

Not Shown

(1) PS/2 Port (Optional)

- 7. Serial Port³
- 8. Connector (2) USB 2.0 port
- 9. RJ-45 Network
- 10. Serial Port (Optional)
- 11. Integrated accessories cable lock
- 12. Power Cord Connector⁴
- 13. Padlock Loop

(1) Parallel Port (Optional via PCIex1 slot)

- (1) 4 Serial Port (Optional via PCIex1 slot)²
- (1) Internal Speaker (Optional)
- (1) Intrusion Sensor (Optional)
- 1. Port will be covered up when configured with processor which is without internal graphics.
- 2. Available in select countries only.
- 3. Available On select skus only.
- 4. Power cord connector will be in different position, depends on which power supply configured.

AT A GLANCE

- Windows 10 Pro, Windows 10 Home or FreeDOS
- Intel[®] H470 chipset supporting Intel[®] 10th processors featuring Intel[®] UHD Graphics
- Supports an optional discrete graphics card
- Integrated 10/100/1000 Ethernet Controller or 802.11ac (1x1) Wi-Fi[®] and Bluetooth[®] 4.2 Combo
- Up to 64GB DDR4- 2933 Unbuffered Memory (UDIMM)
- Independent monitor support via VGA and HDMI interfaces
- TPM 2.0 support (either dTPM or fTPM)¹
- Supports both Hard Disk Drives and M.2 PCIe NVMe Solid State Drives
- Up to 10 USB Ports (including native 4 SuperSpeed USB 5Gbps ports and 2 SuperSpeed USB 10Gbps³ and 2 USB 2.0 ports)
- 180W/310W 90% HE power supply
- Security cable lock supported (sold separately)
- Intrusion sensor supported (Optional)
- Optional HP Care Services available; terms and conditions vary by country; certain restrictions and exclusions apply²

1. TPM feature will be supported on machine pre-configured with FreeDOS, and will be default set as enabled in BIOS setup menu if the machine is dTPM, but will be default set as disabled in BIOS setup menu if the machine is fTPM.

2. HP Care Services are optional. Service levels and response times for HP Care Services may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

3. SuperSpeed USB 10Gbps = USB 3.2 Gen2. SuperSpeed USB 5Gbps = USB 3.2 Gen1

NOTE: See important legal disclosures for all listed specs in their respective features sections.

PRODUCT NAME

HP 290 G4 Microtower PC

OPERATING SYSTEM

Preinstalled	Windows 10 Pro 64 ¹ Windows 10 Home 64 ¹
	WINDOWS TO HOME 04*
Pre-installed (other)	FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/

PROCESSORS

Intel[®] Celeron[®] Processors^{2,3}

CPU Intel Celeron G5900 Dual Core 3.4GHz 2666MHz 58W (3.4GHz, 2MB cache, 2 cores)

Intel[®] Pentium[®] Processors^{2,3}

CPU Intel Pentium Gold G6400 Dual Core 4.0GHz 2666MHz 58W (4.0GHz, 4MB cache, 2 cores) CPU Intel Pentium Gold G6600 Dual Core 4.2GHz 2666MHz 58W (4.2GHz, 4MB cache, 2 cores)

Intel 10th Processors

Intel[®] CoreTM i3^{2,3}

CPU Intel Core i3-10100 4C 3.6GHz 2666MHz 65W (3.6GHz, turbo up to 4.1GHz, 6MB cache, 4 cores)

Intel[®] CoreTM i5^{2,3}

CPU Intel Core i5-10400 6C 2.9GHz 2666MHz 65W (2.9GHz, turbo up to 4.0GHz, 12MB cache, 6 cores) CPU Intel Core i5-10500 6C 3.1GHz 2666MHz 65W (3.1GHz, turbo up to 4.2GHz, 12MB cache, 6 cores)

Intel[®] CoreTM i7^{2,3}

CPU Intel Core i7-10700 8C 2.9GHz 2933MHz 65W (2.9GHz, turbo up to 4.6GHz, 16MB cache, 8 cores)

2.Your product does not support Windows 8 or Windows 7, In accordance with Microsoft's support policy, HP does not support the Windows[®] 8 or Windows 7 operating system on products configured with Intel 8th or 9th generation and forward processors or provide any Windows[®] 8 or Windows 7 drivers on http://www.support.hp.com

3. Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. 64-bit computing system required. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

*NOTE: Only available on selected region

CHIPSET

Intel® H470 Chipset

GRAPHICS

Integrated^{4,5}

Intel® UHD Graphics 630 (integrated on 10th Core i processors and Pentium Gold G6600) Intel® UHD Graphics 610 (integrated on Pentium Gold G6400 and Celeron)

Discrete Graphics

```
AMD Radeon<sup>™</sup> RX550X 4GB GFX
AMD Radeon<sup>™</sup> 520 1GB GFX
NVIDIA® GeForce® GT730 2GB GFX
NVIDIA® GeForce® GTX1660 Super 6GB GFX<sup>*</sup>
```

4. HD content required to view HD images.

5. Integrated Intel software is available on select models only and requires separately purchased projector, tv or computer monitor with an integrated or external receiver. External receivers connect to the projector, tv or computer monitor via a standard VGA, HDMI cable, also sold separately.

*NOTE: Available in select countries only

MEMORY⁶

Form Factor	Туре	Maximum	# of Slots	
Microtower	DDR4 2933 (Transfer rates up to 2933 MT/s) DDR4 2666 (Transfer rates up to 2666 MT/s)	64 GB capacity	2 DIMM	
4GB DDR4-2933 UDIMM NECC (1	1x4GB)			
8GB DDR4-2933 UDIMM NECC (*	8GB DDR4-2933 UDIMM NECC (1x8GB)			
8GB DDR4-2933 UDIMM NECC (2	8GB DDR4-2933 UDIMM NECC (2x4GB)			
16GB DDR4-2933 UDIMM NECC	(2x8GB)			
16GB DDR4-2933 UDIMM NECC	16GB DDR4-2933 UDIMM NECC (1x16GB)			
64GB DDR4-2933 UDIMM NECC	64GB DDR4-2933 UDIMM NECC (2x32GB)			
4GB DDR4-2666 UDIMM NECC (1x4GB)				
8GB DDR4-2666 UDIMM NECC (1	8GB DDR4-2666 UDIMM NECC (1x8GB)			
8GB DDR4-2666 UDIMM NECC (2x4GB)				
16GB DDR4-2666 UDIMM NECC (1x16GB)				
16GB DDR4-2666 UDIMM NECC (2x8GB)				
64GB DDR4-2666 UDIMM NECC	(2x32GB)			

6. Memory modules support data transfer rates up to 2933 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate. **NOTE:** DDR4-2933 UDIMM is only available for 10th Gen i7 processor.

STORAGE

SATA3 - 3.5" or 2.5" 6Gb/s HDDs

2TB 7200 RPM SATA Hard Disk Drive 1TB 7200 RPM SATA Hard Disk Drive 500GB 7200 RPM SATA Hard Disk Drive

Solid State Drives

128GB M.2 NVMe 256GB M.2 NVMe 512GB M.2 NVMe

SD Card Reader⁷ SD/SDHC/SDXC SD Card Reader

Intel Optane Memory⁷

SSD Intel 16GB 2280 Optane Memory

7. Optional per configuration

OPTICAL DISC DRIVES

DVD-ROM 9.5mm DVD-Writer⁸ 9.5mm

R HD-DVD disks cannot be played on this drive. No support for DVD-PA

8. HD-DVD disks cannot be played on this drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

NETWORKING⁹

Ethernet (RJ-45) Integrated 10/100/1000M GbE LAN

Wi-Fi[®] and Bluetooth[®]

802.11ac (1x1) Wi-Fi® and Bluetooth® 4.2 Combo

9. Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited.

AUDIO / MULTIMEDIA

Integrated Hi-Definition Audio Combo Jack, Headphone / Microphone Line-in / Line-out (3.5mm)

KEYBOARDS AND POINTING DEVICES¹⁰

Keyboard

USB Business Slim Wired Keyboard HP USB Wired Keyboard Business Slim USB Antimicrobial Wired Keyboard (China) Business Slim PS/2 Wired Keyboard (for machine configured with PS/2 port) No KB Option

Mouse

Antimicrobial USB Mouse (China) HP Optical USB Mouse Universal Wired USB Mouse USB Hardened Mouse (Specific region) HP PS/2 Mouse (for machine configured with PS/2 port) No Mouse Option

10. Keyboards and mouse are optional or add-on features.

PORTS

Front

Slim-height Bay - supporting an optical disk drive (Optional) Power Button Combo jack, Headphone / Microphone SD Card Reader (Optional) (2) SuperSpeed USB 10Gbps port** (4) SuperSpeed USB 5Gbps port**

Not Shown

(1) PCI Express x16
 (1) PCI Express x1
 (1) Full-height PCI (Available on selected sku)
 (1) M.2 for WLAN
 (1) M.2 2242/2280 storage

Rear

Audio Line out Audio Line in HDMI Port VGA Port Serial Port (Optional on selected sku) 2nd Serial Port (Optional) Standard Lock Slot (2) USB 2.0 port (2) USB 2.0 port (Optional on selected sku) RJ-45 Network connector Power cord connector Padlock loop Integrated accessories cable lock

Not Shown

(1) PS/2 Port (Optional)
 (1) Parallel Port (Optional via PCIex1 slot)
 (1) 4x Serial port (Optional via PCIex1 slot)*
 (1) Internal Speaker (Optional)
 (1) Intrusion Sensor (Optional)

NOTE*: Available in select countries only. NOTE**: SuperSpeed USB 10Gbps = USB 3.2 Gen2. SuperSpeed USB 5Gbps = USB 3.2 Gen1

BAYS

- (1) 9.5mm external slimline ODD bay (Optional)
- (1) 3.5" or 2.5" internal HDD or bay
- (1) 3.5 or 2.5" internal HDD bay (share bay with caddy)

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Security and Protection

McAfee* LiveSafe^{TM 12}

Productivity

Buy Office (sold separately) Dropbox¹³

ODD Playback sMedio True DVD for HP

Movies

Netflix¹⁴

App Stores and Content Purchasing Amazon¹⁴

HP Utilities and Support

HP Documentation HP JumpStarts HP Audio Switch¹⁵ HP Support Assistant

BTB HP Setup Integrated OOBE

Hardware Enabling Drivers or software utility HP System Event Utility

12. Free 1-year subscription of McAfee LiveSafe service included. Internet access required and not included. Subscription required after expiration 13. New Dropbox users are eligible to get 25 GB of Dropbox space free for 12 months from date of registration. For complete details and terms of use, including cancellation policies, visit the Dropbox website at https://www.dropbox.com/help/space/hp-promotion. Internet service required and not included.

14. Internet access required and not included.

15. Easily switch between speaker and microphone sources with intuitive controls and a consistent app experience.

***NOTE**: Available in Latin America countries only.

POWER SUPPLY¹⁶

180 W ENERGY® STAR® Libra2 EPA90 (Gold) Full range 115V/230V 310 W SFF ENTL EPA90 (Gold) Full range 115V/230V 500 W EPA90 (Gold) Full range 115V/230V

16. All power supplies are not available in every region.

DIMENSIONS AND WEIGHT

Dimensions

6.12 x 11.93 x 13.28 in (155 x 303 x 337 mm)

Weight

10.4 lbs / 4.7 kg

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's recirculated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign
 matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range	Operating: 5° to 35° C ¹⁷ Non-operating: -30° to 60° C ¹⁷
Relative Humidity	Operating: 5% to 90% (non-condensing at ambient) Non-operating: 5% to 90% (non-condensing at ambient)
Maximum Altitude (unpressurized)	Operating: 5000 m Non-operating: 50000ft (15240 m)

17. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

Eco-Label Certifications & declarations	http://www.epeat.net for regi	arks: here applicable. EPEAT ® registra stration status by country. Search ar generator accessories at http:// ng to IEEE 1680.1-2018 EPEAT®. Status va	tion varies by country. See keyword generator on HP's www.hp.com/go/options.
System Configuration	The configuration used for the Energy model is based on a "Typically Confid		Emissions data for the Desktop
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	28.12W	28.27W	28.27W
Normal Operation (Long idle)	26.34W	26.51W	26.51W
Sleep	1.66W	1.67W	1.67W
Off	0.29W	0.30W	0.30W

DA - 16653 Worldwide QuickSpecs — Version 3 — 7.21.2020

	family. HP computers marked with th Environmental Protection Agency (EF does not offer ENERGY STAR® compli configured PC featuring a hard disk d operating system.	PA) ENERGY STAR [®] specifications ant configurations, then energy	for computers. If a model family efficiency data listed is for a typica	
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Short idle)	96 BTU/hr	96 BTU/hr	96 BTU/hr	
Normal Operation (Long idle)	90 BTU/hr	90 BTU/hr	90 BTU/hr	
Sleep	6 BTU/hr	6 BTU/hr	<u>6 BTU/hr</u>	
Off	1 BTU/hr NOTE: Heat dissipation is calculated to for one hour.	1 BTU/hr based on the measured watts, as	1 BTU/hr suming the service level is attaine	
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)		Sound Pressure (L _{pAm} , decibels)	
Typically Configured - Idle	3.7		24.7	
Fixed Disk - Random writes	4.1		29.8	
Longevity and Upgrading	This product can be upgraded, pos features and/or components contai Spare parts are available throughou of production.	ned in the product may include	:	
Batteries	This battery(s) in this product comp Batteries used in the product do no Mercury greater the1ppm by weigh Cadmium greater than 20ppm by w Battery size: CR2032 (coin cell)	ot contain: t		
	Battery type: Lithium			
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equip (WEEE) Directive - 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). 		trical and Electronic Equipment (State of California; Safe	
	ISO1043.	25 grams used in the product a post-consumer recycled plasti	re marked per ISO11469 and c (by wt.)	
Packaging Materials	External: PAPER/Paperboa		1220 g	
	Internal: PAPER/Molded P		520 g	
		lene low density - LDPE	53 g	
Material Usage	This product does not contain any of to the HP General Specification for http://www.hp.com/hpinfo/globalcitiz	the Environment at		

	 Asbestos Certain Azo Colorants Certain Brominated Flame Retardants - may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel - finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyl (PBBs) Polybrominated Biphenyl Oxides (PBBCs) Polybrominated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) - except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tchittd Tin (TET) Tributtd Tin Oxide (TETO)
Packaging Usage	 Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency.
End-of-life Management and Recycling	 Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report http://www.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/ PC_GBU_Product_Design_ISO_14K_Certificate.pdf and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

SERVICE AND SUPPORT

On-site Warranty 1: Available three-year (3-3-3) or one-year (1-1-1) limited warranty (varies by country) delivers on-site, next business day 2 service for parts and labor and complimentary limited technical support.3 Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack.4 To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country. **NOTE 3:** Technical support applies only to HP-configured and third-party HP qualified hardware and software.

NOTE 4: Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

GRAPHICS

• •	Core i7/i5/i3/Pentium G6500 and above processors) Pentium G6400 and below/ and Celeron)
DisplayPort [™]	Multimode capable; supports HDCP, DisplayPort [™] Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays (including the integrated panel)
Memory	Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Graphics Memory	Windows 10: >4 GB
Maximum Color Depth	32 bits/pixel
Graphics/Video API Support	10 th Generation Intel [®] Core Processors, Pentium and Celeron With Intel [®] UHD Graphics 630 Pentium [®] and Celeron [®] With Intel [®] UHD Graphics 610
Supported Display Resolutions and Refresh Rates	Max. Resolution (VGA) 2048 x 1536@60Hz Max. Resolution (HDMI) 4096 x 2160@60Hz
Note: The actual amount of maximum graphi	cs memory can be less than the amounts listed above depending upon your computer's configuration.

Note: The actual amount of maximum graphics memory can be less than the amounts listed above depending upon your computer's configuration. **Note:** other resolutions may be available but are not recommended as they may not have been tested and qualified by HP <u>Only supported on displays connected to the external DisplayPortTM connector.</u>

AMD Radeon[™] R7 430 2GB Graphics Card

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	2GB(64-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(VGA)	2048x1536
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	yes
Rear I/O connectors(bracket)	VGA+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

AMD® Radeon[™] RX550X 4 GB FH PCIe x16

Technical Specifications - Graphics

Engine Clock	1183MHz
Memory Clock	6 Gbps
Memory Size(width)	4 GB(128-bit)
Memory Type	GDDR5
Max. Resolution(HDMI)	4096x2160 @ 60Hz
Max. Resolution(DP)	5120x2880 @ 60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	HDMI, DPx2
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP (low profile) PCB with FH/LP bracket

AMD Radeon[™] 520 1GB Graphics Card

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	1GB(32-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(VGA)	2048x1536
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	yes
Rear I/O connectors(bracket)	VGA+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

NVIDIA® GeForce® GTX 1660 Super 6GB Graphics Card

Engine Clock	1785 MHz
Memory Clock	7000 MHz
Memory Size(width)	6GB(192-bit)
Memory Type	256M x 32 GDDR6 @6pcs
Max. Resolution(DVI)	7680x4320@120Hz
Max. Resolution(DP)	7680x4320@120Hz
Multi Display Support	3 displays
HDCP Compliance	yes
Rear I/O connectors(bracket)	DVI-D+DP+HDMI
Cooling(active/passive)	Active fan-sink(Active cooling with dynamic speed)
Total power consumption(W)	<125W
PCB form-factor with bracket	FH PCB with FH bracket

Technical Specifications - Storage

STORAGE*

HP 2 TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity	2 TB
Rotational Speed	7,200 rpm
Interface	SATA 6Gb/s NCQ
Buffer Size	64 MB
Logical Blocks	3,907,029,168
Seek Time	Read: <8.5 ms Write: <9.5 ms
Height	1.028 in/26.11 mm
Width	4.0 in/101.6 mm
Operating Temperature	32° to 140° F (0° to 60° C)

1 TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity	1 TB
Rotational Speed	7,200 rpm
Interface	Serial ATA 3.0 (6.0 Gb/s)
Buffer Size	32 MB
Logical Blocks	1,953,525,168
Seek Time	Single Track: 2.0 ms Average: 11 ms Full-Stroke: 21 ms
Height	1 in/2.54 cm
Width	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)

500 GB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity Rotational Speed Interface	500 GB 7,200 rpm Serial ATA 3.0 (6.0 Gb/s)
Buffer Size Logical Blocks Seek Time	32 MB 1,953,525,168 Single Track: 2.0 ms Average: 11 ms Full-Stroke: 21 ms
Height Width Operating Temperature	1 in/2.54 cm Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm 41° to 131° F (5° to 55° C)

Technical Specifications - Storage

128 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Capacity128GBHeight2.38mm
Height 2.38mm
Length 80mm
Width 22mm
Interface PCIE Gen3x4
Maximum Sequential Read Up to 2800MB/s
Maximum Sequential Write Up to 600MB/s
Logical Blocks 250,069,680
Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]
FeaturesAPST; ASPM L1.2; NVME spec 1.2

256 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	256GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3x4
Maximum Sequential Read	Up to 2700MB/s
Maximum Sequential Write	Up to 1000MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

512 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	512GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3x4
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

256 GB M.2 2280 PCIe NVMe SSD

Technical Specifications - Storage

Drive Weight	< 10g
Capacity	256 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 780MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

512 GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	512 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 860MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

500 GB 7200RPM 2.5in SATA HDD

Capacity	500 GB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	32 MB
Logical Blocks	976,773,168
Seek Time	12 ms (Average)
Height	0.267 in/6.8 mm (nominal)
Width (nominal)	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

1TB 7200RPM 2.5in SATA HDD

Technical Specifications - Storage

Capacity	1 TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	32 MB
Logical Blocks	1,953,525,168
Seek Time	12 ms (Average)
Height	0.374 in/9.5 mm (nominal)
Width (nominal)	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

Technical Specifications – Optical Drives

OPTICAL DISC DRIVES

HP 9.5mm Desktop G2 Slim DVD Writer Drive

Height	9.5 mm height	
Orientation	Either horizontal or vertical	
Interface type	SATA/ATAPI	
Disc recording capacity	Up to 8.5 GB DL or 4.7 GB s	tandard
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9	9.5 x 127 mm) without bezel
Weight (max)	0.31 lb (140 g)	
Read Speeds	DVD-R DL DVD+R DVD+RW DVD+R DL DVD-R DVD-RW CD-R CD-RW DVD-RW, DVD+RW DVD-RW, DVD+R DL DVD-R DL, DVD+R DL DVD+R, DVD-R DVD-ROM DL, DVD-ROM CD-ROM, CD-R CD-RW	Up to 6X Up to 8X Up to 8X Up to 6X Up to 6X Up to 6X Up to 24X Up to 10X Up to 8X Up to 8X Up to 8X Up to 8X Up to 8X Up to 8X Up to 24X Up to 24X
Access time (typical reads, including settling)	Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)	
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)	
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)	

HP 9.5mm Desktop G2 Slim DVD-ROM Drive

Technical Specifications – Optical Drives

Height	9.5 mm height	
Orientation	Either horizontal or vertical	
Interface type	SATA/ATAPI	
Disc recording capacity	Up to 8.5 GB DL or 4.7 GB s	tandard
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9	9.5 x 127 mm) without bezel
Weight (max)	0.31 lb (140 g)	
Read Speeds	DVD-R DL DVD+R DVD+RW DVD+R DL DVD-R DVD-RW CD-R CD-RW DVD-RW, DVD+RW DVD-RW, DVD+R DL DVD-R DL, DVD+R DL DVD+R, DVD-R DVD-ROM DL, DVD-ROM CD-ROM, CD-R CD-RW	Up to 6X Up to 8X Up to 8X Up to 6X Up to 6X Up to 6X Up to 24X Up to 10X Up to 8X Up to 24X Up to 24X
Access time (typical reads, including settling)	Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)	
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)	
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)	

Technical Specifications – Networking

NETWORKING

10/100/1000 NIC	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s	
	Power Management	ACPI compliant - multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption	
	Performance Features	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K	
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status	
	Interface	PCIe + SMBus	
	NIC Device Driver Name	me PCIe GBE Ethernet Family Controller	

Realtek 802.11ac (1x1) W	/i-Fi® and Bluetooth®	4.2 Combo *
Wireless LAN Standards ¹	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac 1. Wireless access point and Internet service required and not included. Availability of public wireless access points limited.	
Interoperability	Wi-Fi® certified modules	
Frequency Bands	802.11b/g/n N(• 2.402 - 2.482 GHz TE: The FCC has declared products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 & 15.249 or otherwise disable those channels.
	802.11a/n	 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz
Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz) 	
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM	
Security ²	 IEEE and 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication 	

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Technical Specifications – Networking

	 WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI 2 Check latest software/driver release for updates on supported security features. 			
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)	Ad-hoc (Peer to Peer)		
Roaming	IEEE 802.11 compliant roaming between	access points		
Output Power ³	 802.11b : +14dBm minimum 802.11g : +12dBm minimum 802.11a : +12dBm minimum 802.11n HT20(2.4GHz) : +12dBm minimum 802.11n HT40(2.4GHz) : +12dBm minimum 802.11n HT20(5GHz) : +10dBm minimum 802.11n HT40(5GHz) : +10dBm minimum 802.11ac VHT80(5GHz) : +10dBm minimum 3. Maximum output power may vary by country according to local regulations. 			
Power Consumption	 Transmit mode2.0 W Receive mode1.6 W Idle mode (PSP)180 mW(WLAN Associated) Idle mode50 mW(WLAN unassociated) Connected Standby 10mW Radio disabled8 mW 			
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode			
Receiver Sensitivity ⁴	 802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.11ac, MCS9 : -59dBm maximum 802.11ac, MCS9 : -59dBm maximum 4 Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (0FDM modulation). 			
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth [®] communications			
Form Factors	PCI-Express M.2 MiniCard			
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm			
Weight	Туре 2230 : 2.8g			
Operating Voltage	3.3v +/- 9%	3.3v +/- 9%		
Temperature	Operating: 14° to 158° F (-10° to 70° C) Non-operating: -40° to 176° F (-40° to 80° C)			
Humidity	Operating:10% to 90% (non-condensing)Non-operating:5% to 95% (non-condensing)			

Technical Specifications – Networking

Altitude	Operating: Non-operating:	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber - Radio OFF; LED White - Radio ON		
HP Integrated Module with Blueto	oth 4.0/4.1/4.2 Wireless Technology		
Bluetooth [®] Specification	4.0/4.1/4.2 Compliant		
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up	o to 2.17 Mbps	
	BLE : 1 Mbps data rate; throughput up to Legacy : Synchronous Connection Oriente		
	Legacy : Asynchronous Connection Less kbps symmetric (3-EV5)	inks 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864	
Transmit Power	The Bluetooth [®] component shall operate transmit power of + 4 dBm for BR and ED	e as a Class II Bluetooth [®] device with a maximum IR.	
Receiver Sensitivity Legacy			
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW		
Range	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)		
Electrical Interface	USB 2.0 compliant		
Bluetooth [®] Software Supported Link Topology	Microsoft Windows Bluetooth [®] Software		
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark		
Certifications Bluetooth [®] Profiles Supported	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support		
Certifications Bluetooth [®] Profiles Supported	BT4.1-ESR 5/6/7 ComplianceLE Link Layer PingLE Dual ModeLE Link LayerLE Low Duty Cycle Directed AdvertisingLE Low Duty Cycle Directed AdvertisingLE L2CAP Connection Oriented ChannelsTrain Nudging & Interlaced ScanBT4.2 ESR08 ComplianceLE Secure Connection- Basic/FullLE Privacy 1.2 -Link Layer PrivacyLE Privacy 1.2 -Extended Scanner Filter PoliciesLE Data Packet Length ExtensionFAX Profile (FAX)Basic Imaging Profile (BIP)2Headset Profile (HSP)Hands Free Profile (HFP)		

Technical Specifications – Networking

Advanced Audio Distribution Profile (A2DP)

Technical Specifications - Audio

HIGH DEFINITION AUDIO

Туре	Integrated	
HD Stereo Codec	Realtek ALC3601	
Audio I/O Ports	Front side Combo jack for supporting CTIA, Rear side Line-in/ Line-out/ Mic-in jacks	
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered externally.	
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.	
HD Audio Codec	Realtek ALC3601	
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1K/ 48 K/96K / 192K Hz for DAC and 44.1K/ 48K/ 96K/ 192K Hz Hz for ADC	
Wavetable Syntheses	Yes	
Analog Audio	Yes	
# of Channels on Line-Out	Stereo	
Internal Speaker	Yes	
External Speaker Jack	2W class D mono amplifier for the internal speaker only. External speakers must be powered externally.	
NOTE*: Optional		

Technical Specifications - Power

POWER SUPPLY

Operating Voltage Range	90 - 264 VAC
Rated Voltage Range	100-240V AC
Rated Line Frequency	50/60 HZ
Operating Line Frequency	47 - 63 Hz
Rated Input Current	180W : <2.3A; 310W: <4A 500W: <6A
Rated Input Current with Energy Efficient* Power Supply	180W active PFC 87/90/87% efficient at 20/50/100% load (115V) 88/92/88% efficient at 20/50/100% load (230V); 310W active PFC 87/90/87% efficient at 20/50/100% load (115V) 88/92/88% efficient at 20/50/100% load (230V) 500W active PFC 87/90/87% efficient at 20/50/100% load (115V) 88/92/88% efficient at 20/50/100% load (230V)
DC Output	+12.1V
Current Leakage (NFPA 99: 2102)	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
Power Supply Fan	180W/310W: 70*25mm (linear type) 500W: 70*25mm (PWM type)

Technical Specifications – Weights and Dimensions

WEIGHT AND DIMENSIONS

Chassis (W x H x D)	6.12 x 11.93 x 13.28 in (155 x 303 x 337 mm)
System Volume	15.1 L
System Weight*	10.4 lbs / 4.7 kg
Max Supported Weight (desktop orientation)	N/A
Packaged (H x W x D)	11.3 x 15.75 x 19.65 in 287 x 400 x 499 mm
Shipping Weight	17.64lb / 8 kg
Palletization Profile	6 units per layer 7layer max 42 per pallet Footprint -85.31x39.37x47.24 in (2167 x 1000 x1200 mm)

After-Market Options (availability may vary by region)

AFTERMARKET OPTIONS

Туре	Description	Part #
Memory	HP 4GB DDR4-2666 DIMM	ЗТК85АА
	HP 8GB DDR4-2666 DIMM	ЗТК87АА
	HP 16GB DDR4-2666 DIMM	ЗТК8ЗАА
Storage	HP 500GB SATA 6.0Gb/s Hard Drive	QK554AA
	HP 1TB 7200rpm SATA 6Gbps Hard Drive	QK555AA
	HP PCIe NVME TLC 256GB SSD M.2 Drive	1CA51A/
	HP 256GB SATA TLC Non-SED Solid State Drive	 P1N68AA
	HP 9.5mm G3 8/6/4 SFF G4 400 SFF/MT DVD Writer	1CA53AA
Graphics	NVIDIA® GT 730 2GB DP Card	Z9H51AA
	AMD Radeon TM R7 430 2GB 2DP Card	5JW82AA
Security	HP Business PC Security Lock V3 Kit	3XJ17AA
	HP Keyed Cable Lock 10mm kit	T1A62AA
Adapters	HP HDMI Standard Cable Kit	ТбҒ94АА
	HP USB to Serial Port Adapter	J7B60AA
	HP PCIe x1 Parallel Port Card	N1M40AA
Networking	Intel Ethernet I210-T1 GbE NIC Card	E0X95AA
Input	HP USB Mouse	QY777AA
	HP USB Hardened Mouse	P1N77AA
	HP USB Grey v2 Mouse	Z9H74AA
	HP USB Keyboard	QY776AA
	HP PS/2 Business Slim Keyboard	N3R86AA
	HP USB Business Slim Keyboard	N3R87AA
	HP Backlit USB Mechanical Keyboard	4RV35AA
	HP USB Antimicrobial Slim Keyboard and Mouse	Z9H50AA
Others	HP Business Headset v2	T4E61AA
	HP S101 Speaker bar	5UU40AA

Change Log

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Date of change:	Version History:	Change	Description of change:
June 4, 2020	From v1 to v2	Remove	Nvidia GeForce GT730 2GB Card from Graphics section
June 5, 2020	From V2 to V3	Added	Disclaimer #4 in rear call outs section
July 21, 2020	From V3 to V4	Added	Environmental section